

Trench gate field-stop IGBT, M series 650 V, 30 A low-loss in a TO-220 package

Datasheet - production data

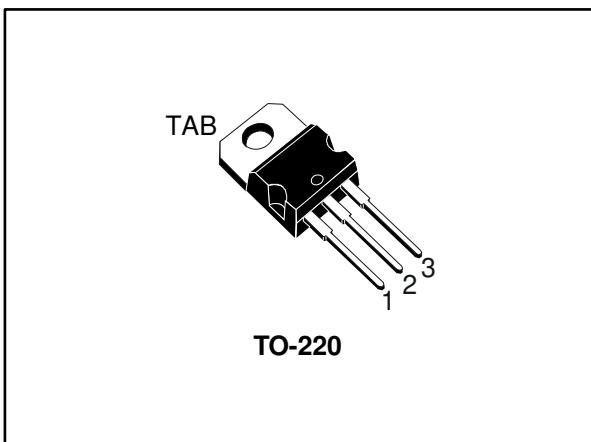
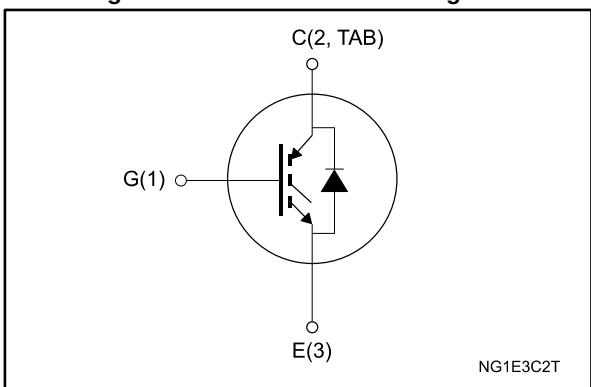


Figure 1: Internal schematic diagram



Features

- 6 μ s of minimum short-circuit withstand time
- $V_{CE(sat)} = 1.55$ V (typ.) @ $I_c = 30$ A
- Tight parameters distribution
- Safer paralleling
- Low thermal resistance
- Soft and very fast recovery antiparallel diode

Applications

- Motor control
- UPS
- PFC

Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the M series of IGBTs, which represent an optimum compromise in performance to maximize the efficiency of inverter systems where low-loss and short-circuit capability are essential. Furthermore, a positive $V_{CE(sat)}$ temperature coefficient and tight parameter distribution result in safer paralleling operation.

Table 1: Device summary

Order code	Marking	Package	Packaging
STGP30M65DF2	G30M65DF2	TO-220	Tube

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage ($V_{GE} = 0$ V)	650	V
I_c	Continuous collector current at $T_c = 25$ °C	60	A
I_c	Continuous collector current at $T_c = 100$ °C	30	A
$I_{CP}^{(1)}$	Pulsed collector current	120	A
V_{GE}	Gate-emitter voltage	±20	V
I_F	Continuous forward current at $T_c = 25$ °C	60	A
I_F	Continuous forward current at $T_c = 100$ °C	30	A
$I_{FP}^{(1)}$	Pulsed forward current	120	A
P_{TOT}	Total dissipation at $T_c = 25$ °C	258	W
T_{STG}	Storage temperature range	-55 to 150	°C
T_J	Operating junction temperature range	-55 to 175	°C

Notes:

(1)Pulse width limited by maximum junction temperature.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case IGBT	0.58	°C/W
R_{thJC}	Thermal resistance junction-case diode	1.47	°C/W
R_{thJA}	Thermal resistance junction-ambient	62.5	°C/W

2 Electrical characteristics

$T_C = 25^\circ\text{C}$ unless otherwise specified

Table 4: Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0 \text{ V}$, $I_C = 250 \mu\text{A}$	650			V
$V_{CE(\text{sat})}$	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}$, $I_C = 30 \text{ A}$		1.55	2.0	V
		$V_{GE} = 15 \text{ V}$, $I_C = 30 \text{ A}$, $T_J = 125^\circ\text{C}$		1.95		
		$V_{GE} = 15 \text{ V}$, $I_C = 30 \text{ A}$, $T_J = 175^\circ\text{C}$		2.1		
V_F	Forward on-voltage	$I_F = 30 \text{ A}$		1.85	2.65	V
		$I_F = 30 \text{ A}$, $T_J = 125^\circ\text{C}$		1.6		
		$I_F = 30 \text{ A}$, $T_J = 175^\circ\text{C}$		1.5		
$V_{GE(\text{th})}$	Gate threshold voltage	$V_{CE} = V_{GE}$, $I_C = 500 \mu\text{A}$	5	6	7	V
I_{CES}	Collector cut-off current	$V_{GE} = 0 \text{ V}$, $V_{CE} = 650 \text{ V}$			25	μA
I_{GES}	Gate-emitter leakage current	$V_{CE} = 0 \text{ V}$, $V_{GE} = \pm 20 \text{ V}$			± 250	μA

Table 5: Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	$V_{CE} = 25 \text{ V}$, $f = 1 \text{ MHz}$, $V_{GE} = 0 \text{ V}$	-	2490	-	pF
C_{oes}	Output capacitance		-	143	-	
C_{res}	Reverse transfer capacitance		-	46	-	
Q_g	Total gate charge	$V_{CC} = 520 \text{ V}$, $I_C = 30 \text{ A}$, $V_{GE} = 0$ to 15 V (see Figure 30: "Gate charge test circuit")	-	80	-	nC
Q_{ge}	Gate-emitter charge		-	18	-	
Q_{gc}	Gate-collector charge		-	32	-	

Table 6: IGBT switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 30 \text{ A}, V_{GE} = 15 \text{ V}, R_G = 10 \Omega$ (see Figure 29: "Test circuit for inductive load switching")		31.6	-	ns
t_r	Current rise time			13.4	-	ns
$(di/dt)_{on}$	Turn-on current slope			1791	-	A/ μs
$t_{d(off)}$	Turn-off-delay time			115	-	ns
t_f	Current fall time			110	-	ns
$E_{on}^{(1)}$	Turn-on switching energy			0.3	-	mJ
$E_{off}^{(2)}$	Turn-off switching energy			0.96	-	mJ
E_{ts}	Total switching energy			1.26	-	mJ
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 30 \text{ A}, V_{GE} = 15 \text{ V}, R_G = 10 \Omega, T_J = 175 \text{ }^\circ\text{C}$ (see Figure 29: "Test circuit for inductive load switching")		30	-	ns
t_r	Current rise time			17	-	ns
$(di/dt)_{on}$	Turn-on current slope			1435	-	A/ μs
$t_{d(off)}$	Turn-off-delay time			116	-	ns
t_f	Current fall time			194	-	ns
$E_{on}^{(1)}$	Turn-on switching energy			0.67	-	mJ
$E_{off}^{(2)}$	Turn-off switching energy			1.36	-	mJ
E_{ts}	Total switching energy			2.03	-	mJ
t_{sc}	Short-circuit withstand time	$V_{CC} \leq 400 \text{ V}, V_{GE} = 13 \text{ V}, T_{Jstart} = 150 \text{ }^\circ\text{C}$	10		-	μs
		$V_{CC} \leq 400 \text{ V}, V_{GE} = 15 \text{ V}, T_{Jstart} = 150 \text{ }^\circ\text{C}$	6		-	

Notes:

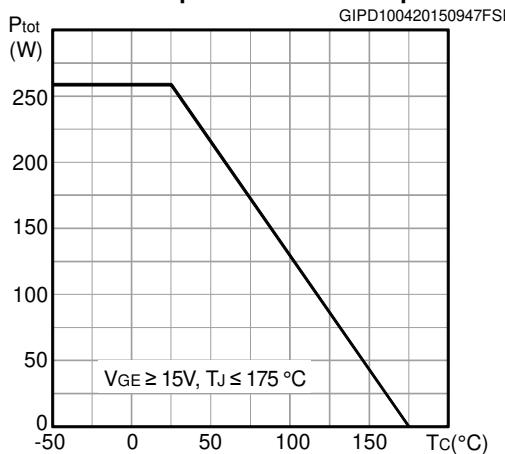
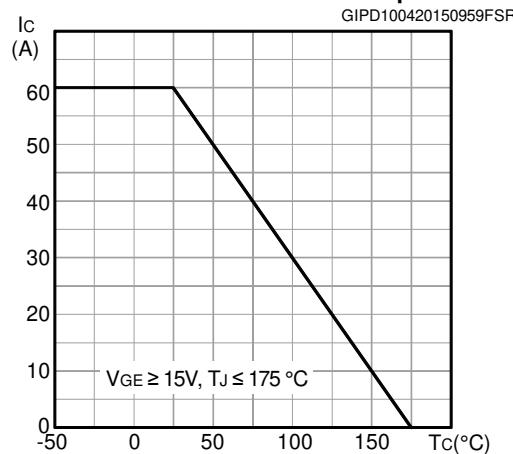
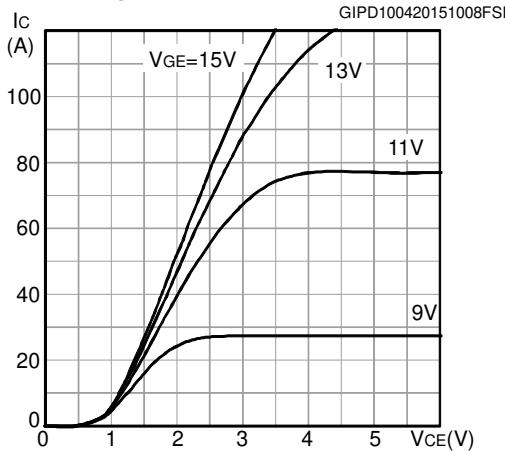
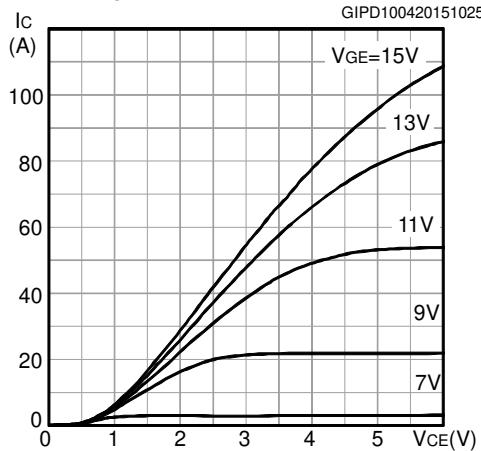
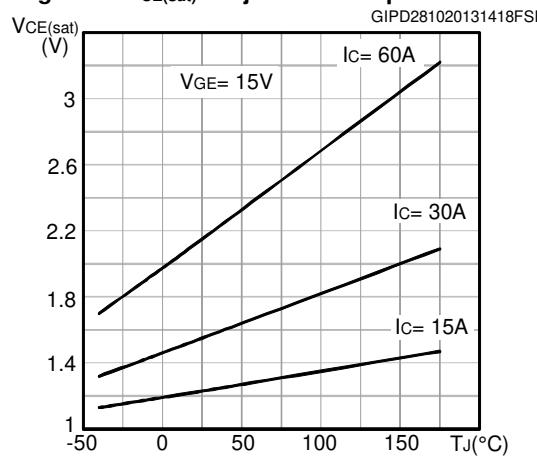
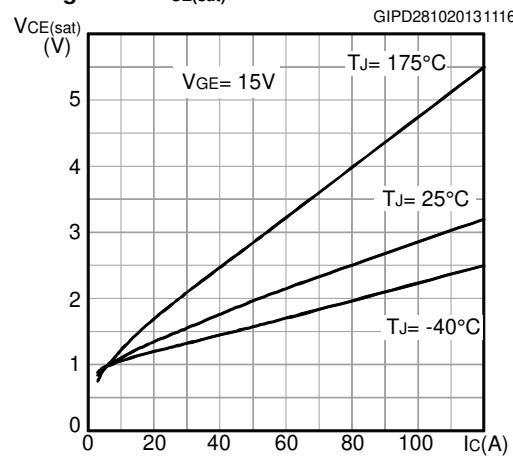
(1) Including the reverse recovery of the diode.

(2) Including the tail of the collector current.

Table 7: Diode switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$I_F = 30 \text{ A}, V_R = 400 \text{ V}, V_{GE} = 15 \text{ V}, di/dt = 1000 \text{ A}/\mu\text{s}$ (see Figure 29: "Test circuit for inductive load switching")	-	140	-	ns
Q_{rr}	Reverse recovery charge		-	880	-	nC
I_{rrm}	Reverse recovery current		-	17	-	A
dI_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	650	-	A/ μs
E_{rr}	Reverse recovery energy		-	115	-	μJ
t_{rr}	Reverse recovery time	$I_F = 30 \text{ A}, V_R = 400 \text{ V}, V_{GE} = 15 \text{ V}, di/dt = 1000 \text{ A}/\mu\text{s}, T_J = 175 \text{ }^\circ\text{C}$ (see Figure 29: "Test circuit for inductive load switching")	-	244	-	ns
Q_{rr}	Reverse recovery charge		-	2743	-	nC
I_{rrm}	Reverse recovery current		-	25	-	A
dI_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	220	-	A/ μs
E_{rr}	Reverse recovery energy		-	320	-	μJ

2.1 Electrical characteristics (curves)

Figure 2: Power dissipation vs. case temperature**Figure 3: Collector current vs. case temperature****Figure 4: Output characteristics ($T_J = 25^\circ\text{C}$)****Figure 5: Output characteristics ($T_J = 175^\circ\text{C}$)****Figure 6: $V_{CE(sat)}$ vs. junction temperature****Figure 7: $V_{CE(sat)}$ vs. collector current**

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Electrical characteristics

Figure 8: Collector current vs. switching frequency

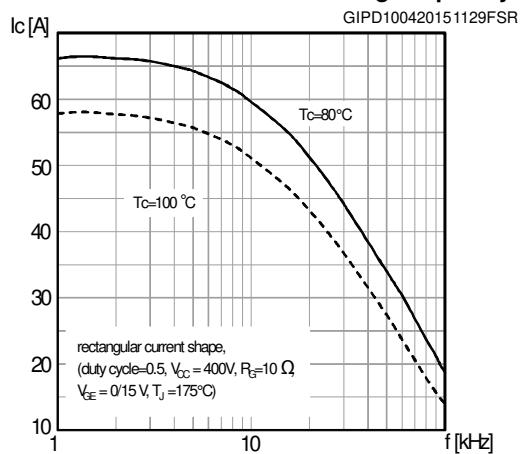


Figure 9: Forward bias safe operating area

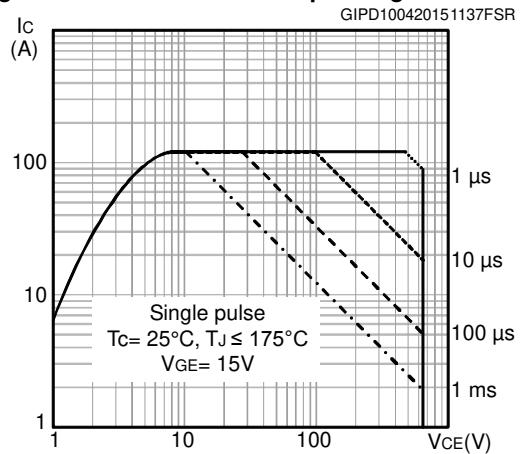


Figure 10: Transfer characteristics

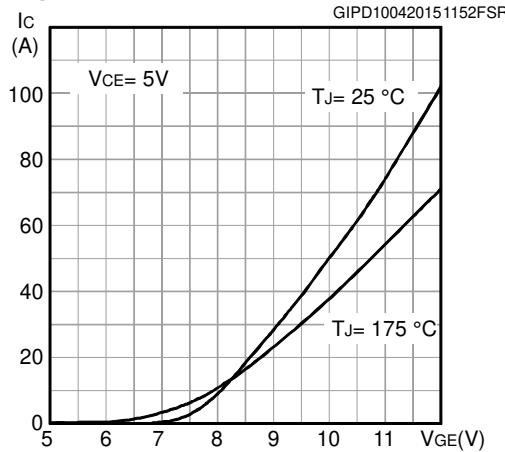


Figure 11: Diode V_F vs. forward current

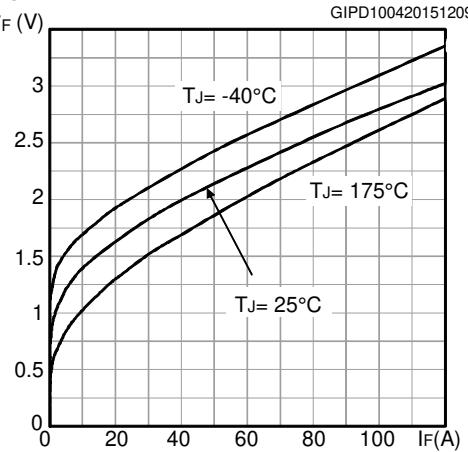


Figure 12: Normalized $V_{GE(\text{th})}$ vs. junction temperature

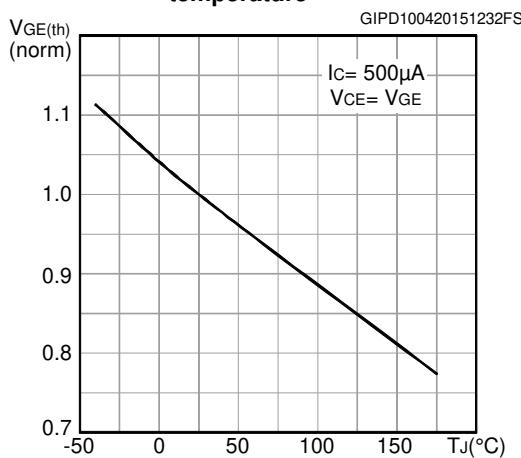
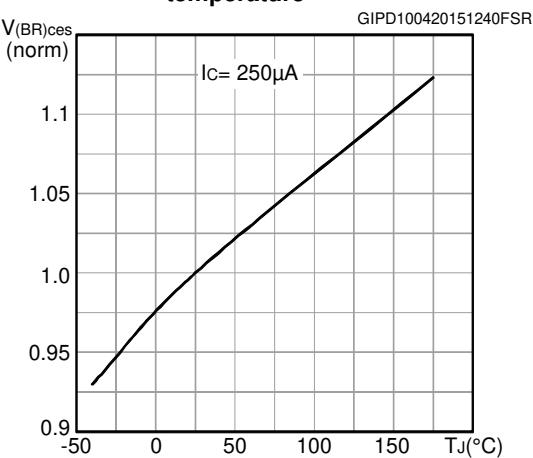


Figure 13: Normalized $V_{(BR)CES}$ vs. junction temperature



Electrical characteristics

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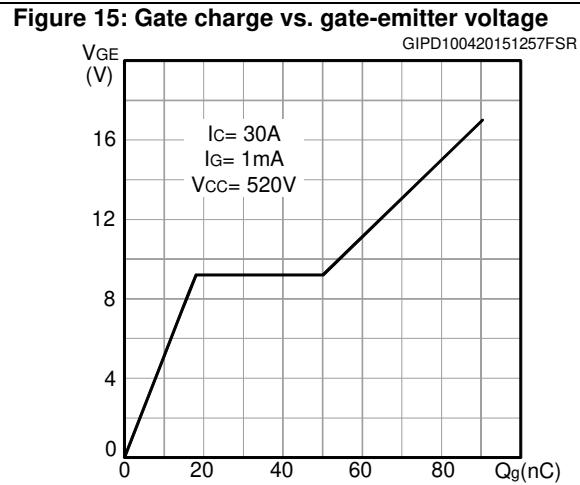
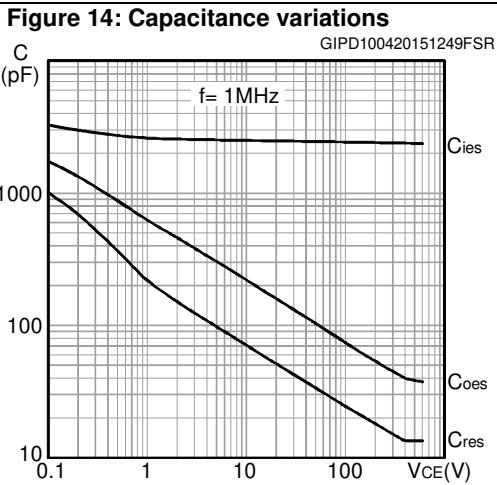


Figure 16: Switching energy vs. collector current

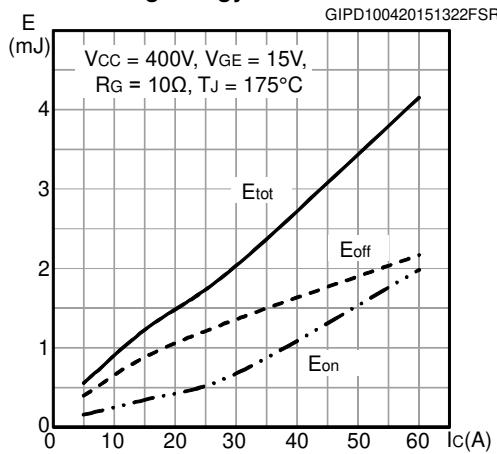


Figure 17: Switching energy vs. gate resistance

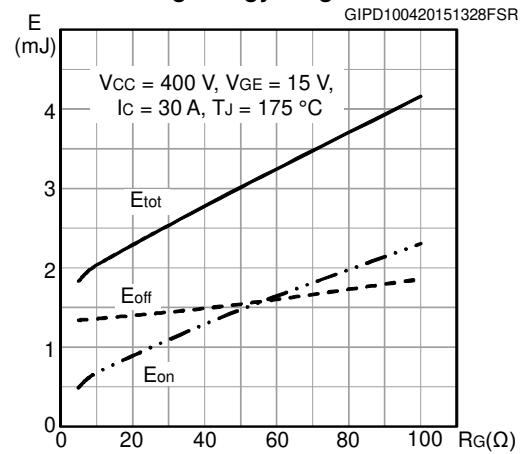


Figure 18: Switching energy vs. temperature

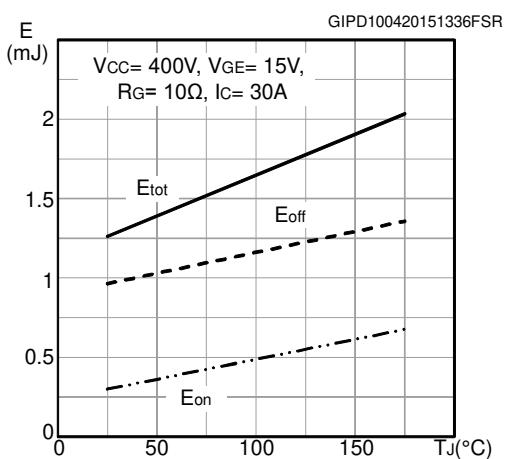
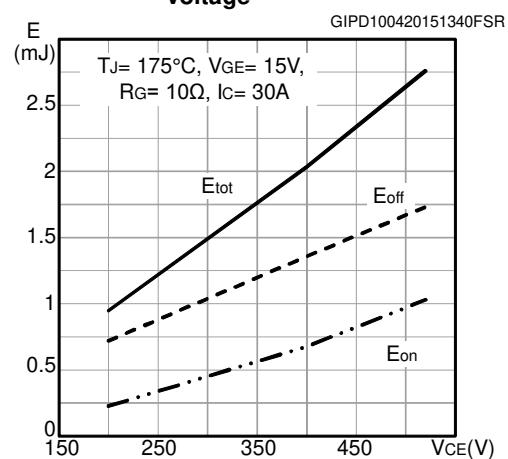


Figure 19: Switching energy vs. collector-emitter voltage



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Electrical characteristics

Figure 20: Short-circuit time and current vs. V_{GE}

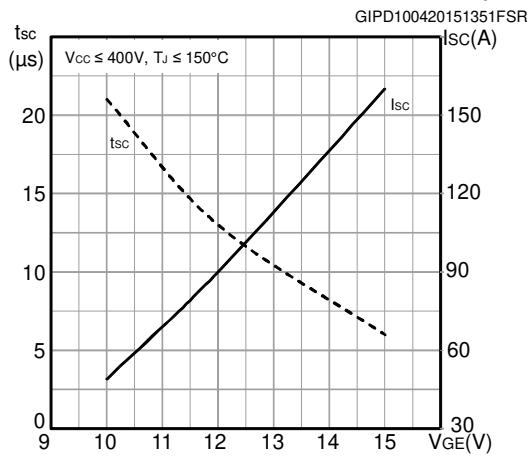


Figure 21: Switching times vs. collector current

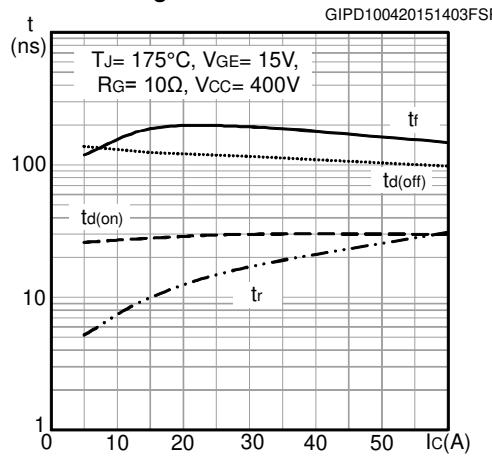


Figure 22: Switching times vs. gate resistance

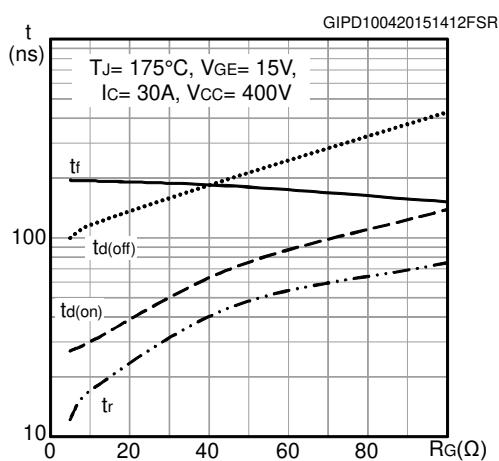


Figure 23: Reverse recovery current vs. diode current slope

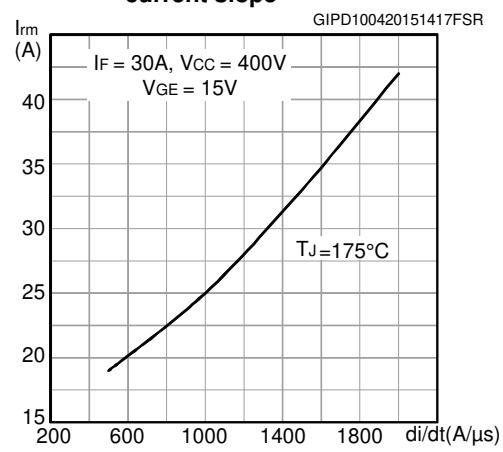


Figure 24: Reverse recovery time vs. diode current slope

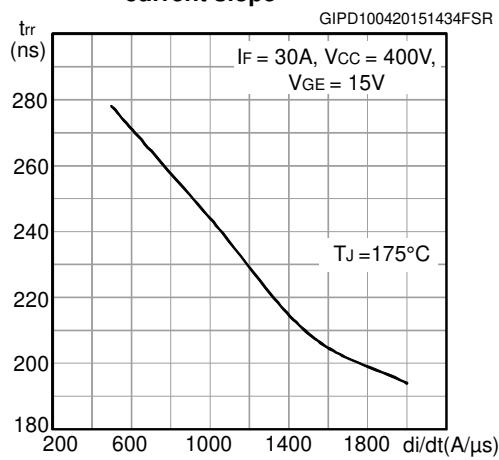


Figure 25: Reverse recovery charge vs. diode current slope

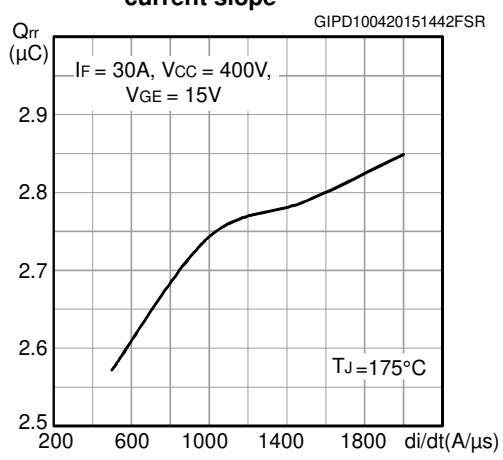
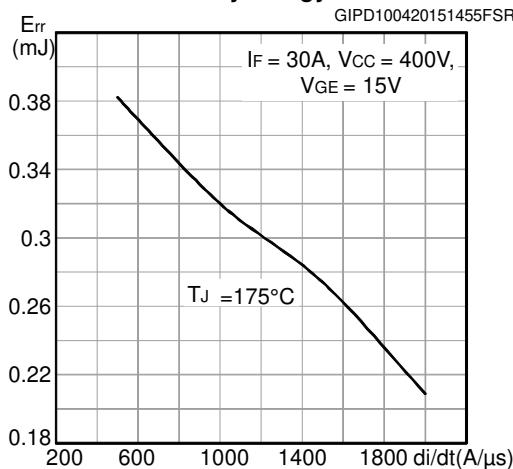
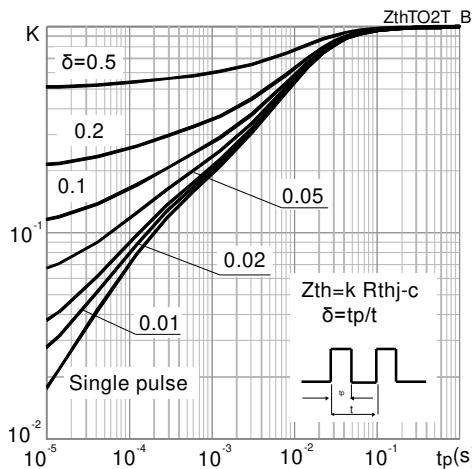
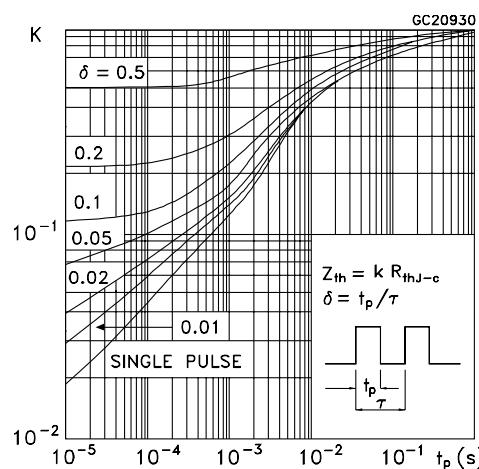
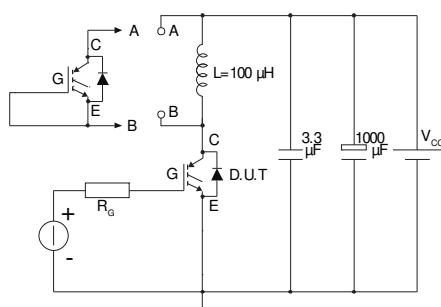


Figure 26: Reverse recovery energy vs. diode current slope**Figure 27: Thermal impedance for IGBT****Figure 28: Thermal impedance for diode**

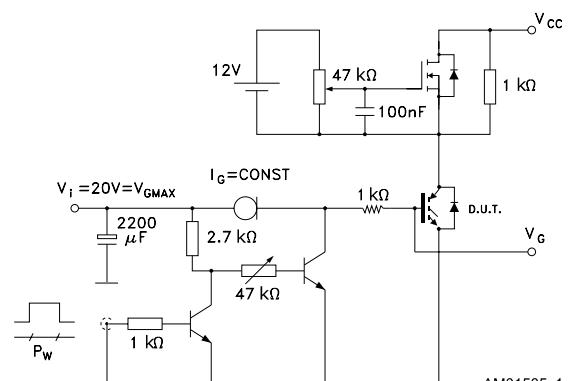
3 Test circuits

Figure 29: Test circuit for inductive load switching



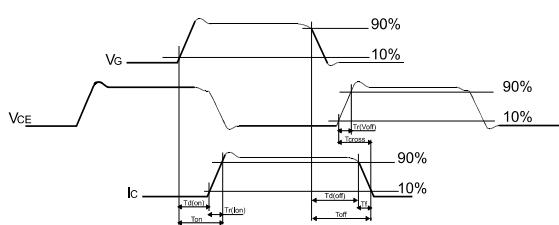
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Figure 30: Gate charge test circuit



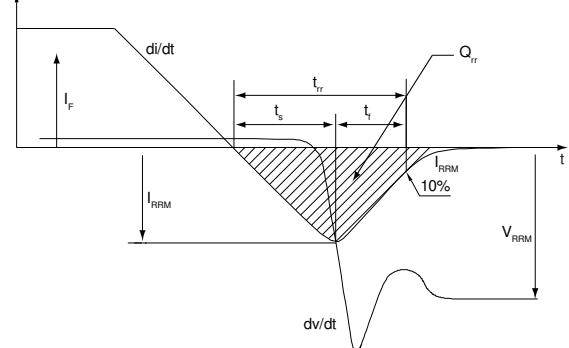
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Figure 31: Switching waveform



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Figure 32: Diode reverse recovery waveform



AM01507v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
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4.1 TO-220 type A package information

Figure 33: TO-220 type A package outline

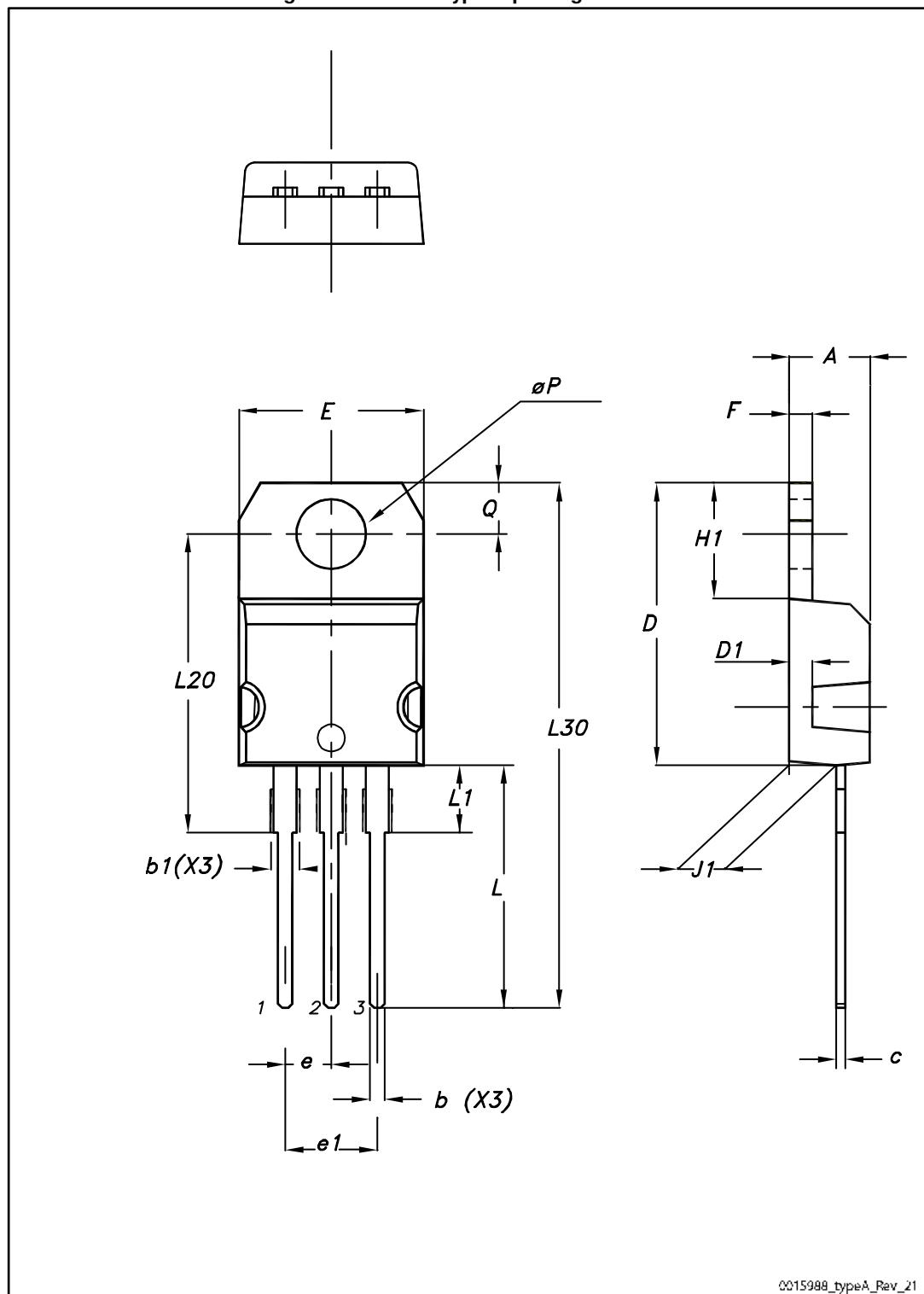


Table 8: TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

5 Revision history

Table 9: Document revision history

Date	Revision	Changes
10-Feb-2015	1	First release.
13-Apr-2015	2	Document status promoted from preliminary to production data. Updated features in cover page. Updated <i>Section 2: "Electrical characteristics"</i> Added <i>Section 2.1: "Electrical characteristics (curves)"</i>
11-Apr-2017	3	Updated document title. Updated <i>Table 4: "Static characteristics"</i> , <i>Table 6: "IGBT switching characteristics (inductive load)"</i> and <i>Table 7: "Diode switching characteristics (inductive load)"</i> . Updated <i>Figure 13: "Normalized $V_{BR}CES$ vs. junction temperature "</i> . Updated <i>Section 4.1: "TO-220 type A package information"</i> . Minor text changes

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